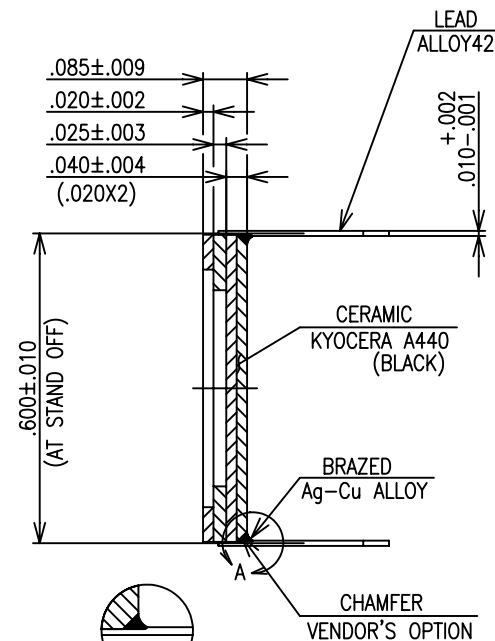
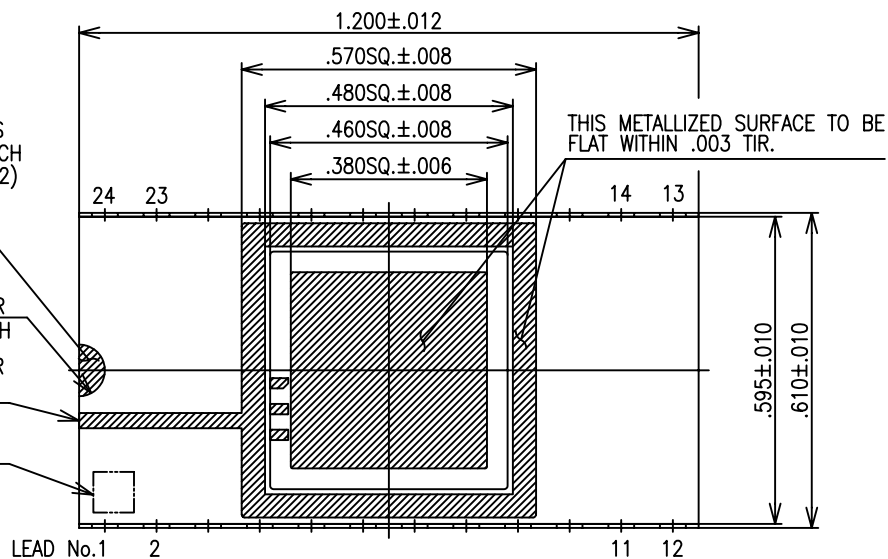
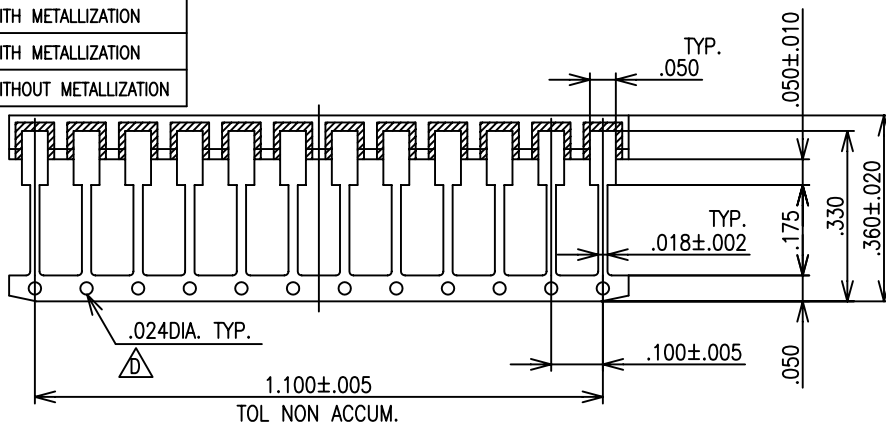


SSM P/N: CSB02491

THIS METALLIZED AREA IS CONNECTED TO DIE ATTACH PAD.(ONLY PART No.01,02)



PART No.	INDEX MARK	LEAD TIED DOWN	NOTCH AREA METALLIZED
01		NIL	WITH METALLIZATION
02		LEAD No.1 ONLY	WITH METALLIZATION
03		NIL	WITHOUT METALLIZATION



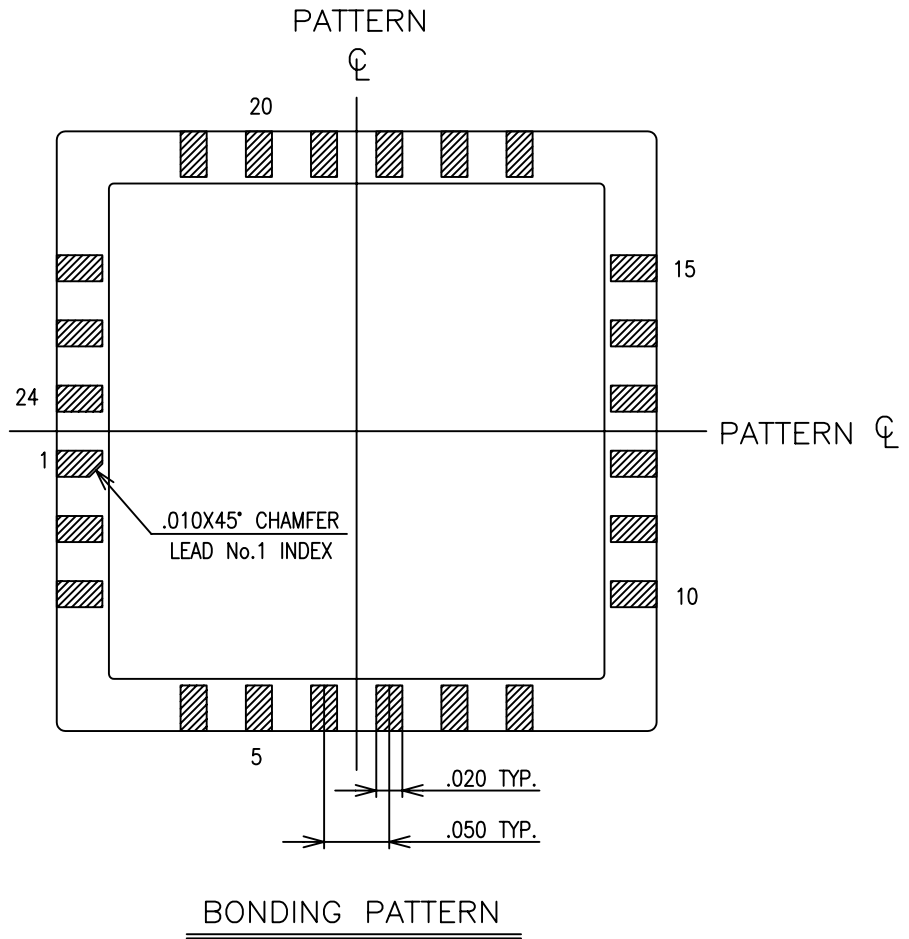
NOTES

1. PLATING THICKNESS TO BE PER CUSTOMER'S SPECIFICATION.
2. SEAL AREA TO BE METALLIZED.
3. DIE ATTACH AREA TO BE METALLIZED.
4. LEAD RESISTANCE : 0.30 OHM MAX.
5. WIRE BOND PAD CONNECTED TO CORRESPONDED OUTER LEADS.
6. MISALIGNMENT OF METALLIZATION PATTERN IN CAVITY SHALL BE ACCEPTED DUE TO LAYER MISALIGNMENT.

SB0241516-3	S=0 D=0
SB0241516-2	S=0 D=1
SB0241516-1	S=0 D=0

MODIFICATION						NAME	TOLERANCE	DRAWN	CHECKED	APPROVED	DATE
							24 LEAD SIDE BRAZED PACKAGE	UNLESS OTHERWISE SPECIFIED	S.S	K.M	T.A
	ADDED : PART No.3 , NOTE 5,6 , DELETED : VENDOR'S OPTION	FEB.13.'08	Y.H	TO.H/M.SU	S.NI	SCALE 4 / 1	MATERIAL AS INDICATED				
	REDRAWN (CONVERTED CAD DATA)	AUG.21.'93	S.SH	H.S/S.F	T.A		±.005				
	CHANGED	DATE	DRAWN	CHECKED	APPROVED		KYOCERA CORPORATION KYOTO JAPAN	DRAWING NO.	KD-78516-D		SHEET 1/2





MODIFICATION						NAME	TOLERANCE	DRAWN	CHECKED	APPROVED	DATE
						24 LEAD SIDE BRAZED PACKAGE	UNLESS OTHERWISE SPECIFIED	M.K	S.T/S.F	T.A	APR.07.'93
						SCALE 10 / 1	MATERIAL				
							THIRD ANGLE PROJECTION				
△	REDRAWN (CONVERTED CAD DATA)	AUG.21.'93	S.SH	H.S/S.F	T.A		KYOCERA CORPORATION KYOTO JAPAN	DRAWING NO.		KD-78516-D	SHEET
	CHANGED	DATE	DRAWN	CHECKED	APPROVED			2 / 2			



